

Hyve Orion Featuring Nvidia HGX B300 Direct Liquid Cooled (DLC)

AI Factory for the Era of Reasoning



Key Features

- NVIDIA Blackwell Ultra with Integrated NVIDIA ConnectX®-8 Networking
- Dual Intel Xeon 6700 Series Processors with P-Cores (350W) TDP
- Direct Liquid Cooled Optimized
- Front IO Serviceable

Specifications

Dimensions	19" 3RU (Height: 130.85MM Width: 447MM Depth: 800MM)	Storage	Up to 8 x Hot-Swap E1.S NVMe Drives
Headnode	Intel	GPU	NVIDIA SXM: HGX™ B300
CPU	Intel Xeon 6700 Series Processors	Thermal Solution	Direct Liquid Cooled (DLC)
BIOS	AMI 64MB SPI	System Management	DC-SCM AST2600 + eRoT (CEC1736)
Socket	LGA-4710		
Memory	32 x DIMMs 6400/5200MT/s (1DPC/2DPC)		
LAN	1 x 1GB RJ45		



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